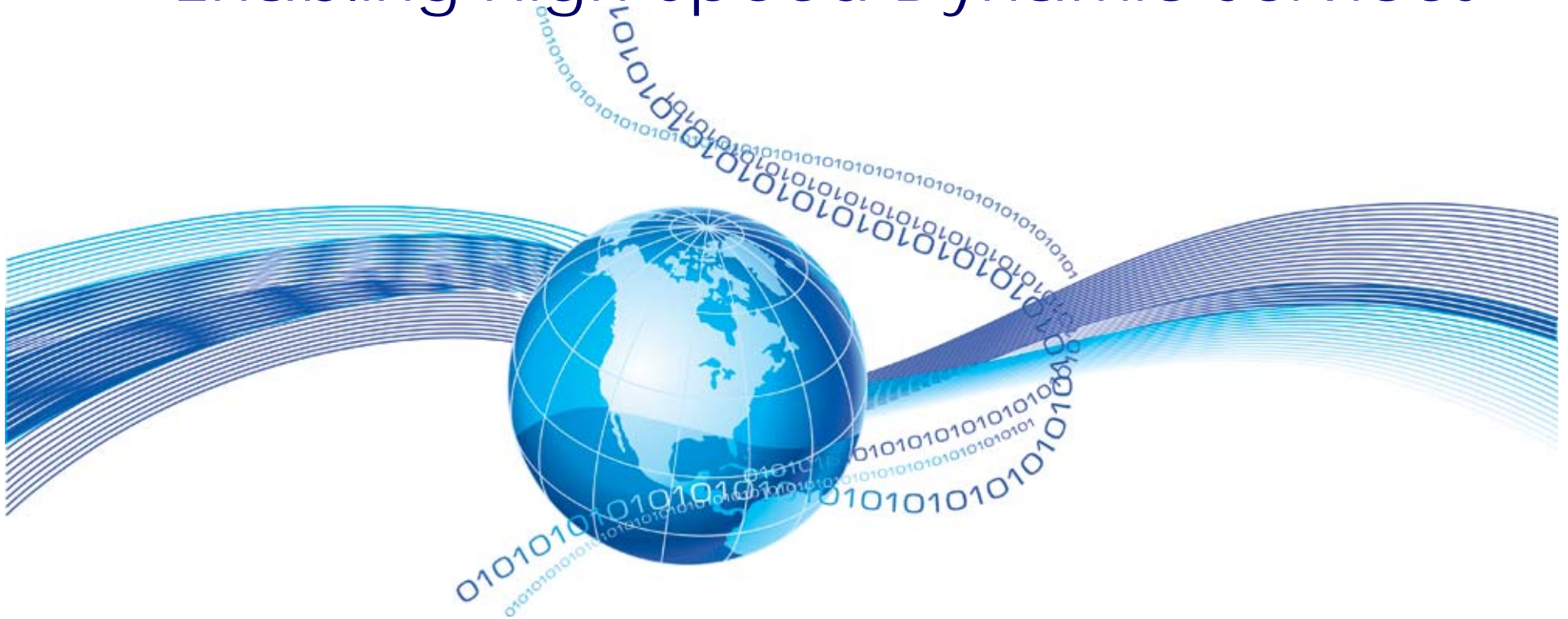


OIF Physical and Link Layer (PLL) 25-28 Gbaud Interoperability 2012 Enabling High-Speed Dynamic Services



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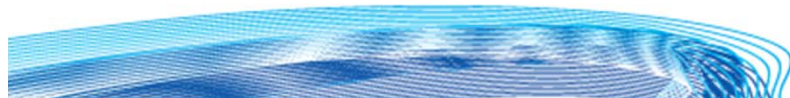
Market Drivers for Physical Layer Electrical Interoperability at 25-28 Gbaud

Market Trend/Needs

- Next generation architectures capable of supporting industry growth rates
- To enable economical adoption of 100Gb/s, definition of signals was required for board-to-board, chip-to-chip and chip-to-module
- Broad deployment through interoperable chips, connectors, and optical modules

Interconnect Challenges

- Ensure robust electrical interfaces able to meet system Bit Error Rate (BER) targets
- Multi-vendor Interoperability
- Defined parameters meeting industry objectives



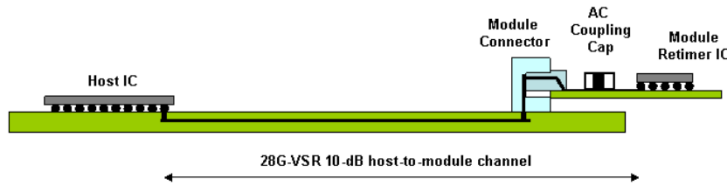
PLL Demo Overview

- PLL Demo includes five individual Interop Demo's made up of ten participating companies and one test equipment vendor
- Three demos focused on Very Short Reach chip-to-module applications based upon CEI-28G-VSR
- Two demos focused on Long Reach backplane applications using CEI-25G-LR
- Plugfests completed in January 2012

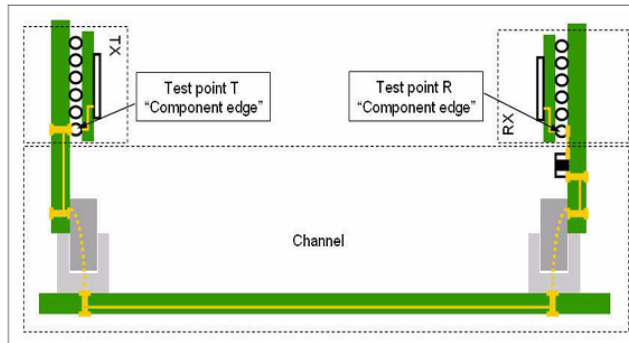


CEI-28G-VSR and CEI-25G-LR Application Overview

- 28G-VSR targeted to chip-to-module channels of up to 10 dB loss



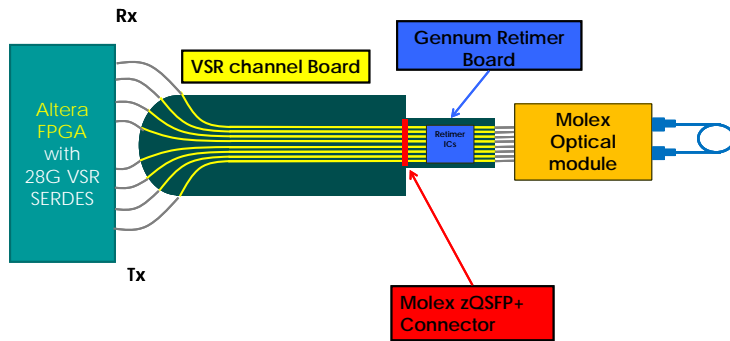
- 25G-LR targeted to backplane channels of up to 25 dB loss



Three CEI-28G-VSR demos

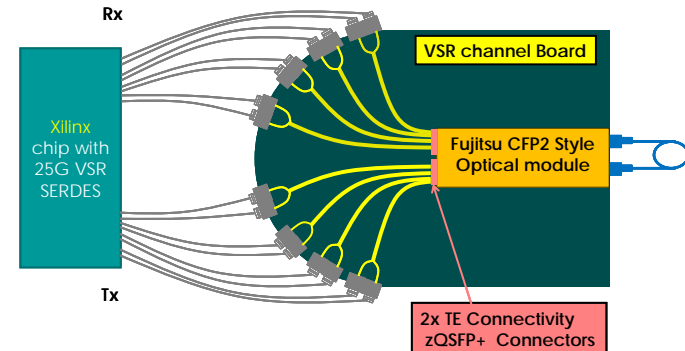
□ Demo No. 1

Altera - Gennum - Molex



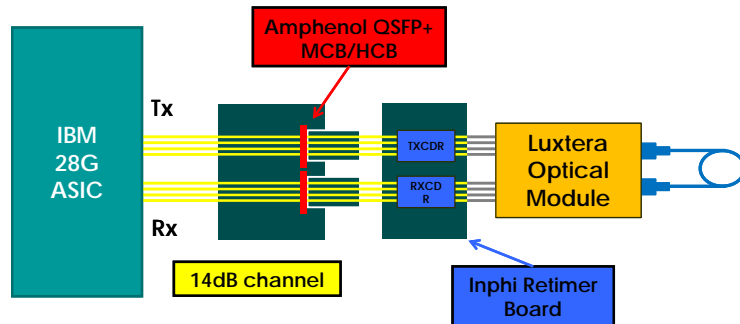
□ Demo No. 2

Xilinx - TE Connectivity - Fujitsu Optical Components



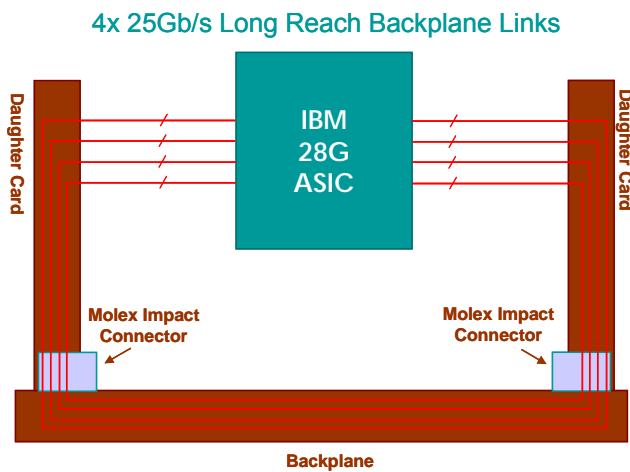
□ Demo No. 3

IBM - Amphenol - Inphi - Luxtera

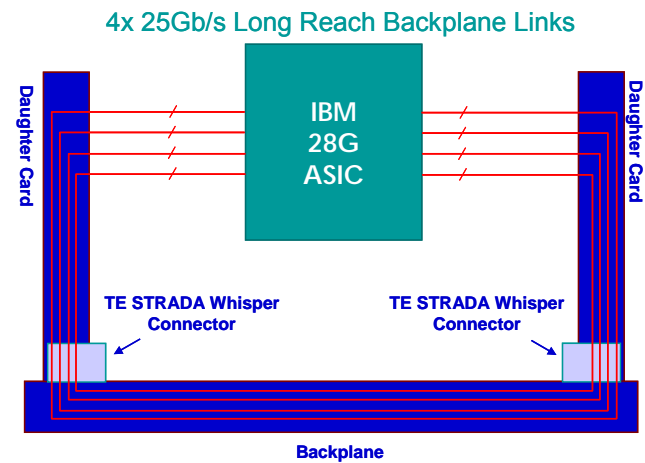


Two CEI-25G-LR demos

- Demo No. 4
IBM - Molex

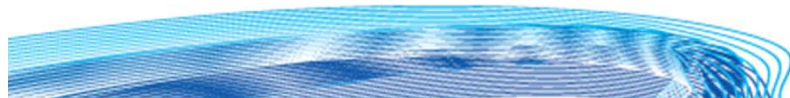


- Demo No. 5
IBM - TE Connectivity



Benefits of PLL Interoperability Demo

- **Demonstration of viability of next generation 25 – 28 Gb/s electrical system interfaces for switches, routers, transport and data center equipment**
- **Validation of interface architectures and constraints as defined in the Implementation Agreement**
- **Demonstration that an Ecosystem is now in place to deliver the next generation of data rates to System OEM vendors and manufacturers**



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